

ABSTRACT OF THE INVENTION

A heat dissipation structure includes a heat sink installed over a heat generating electronic device and a plurality of heat pipes. Proximal ends of the heat pipes are located on the heat sink, and distal ends of the heat pipes extend
5 outside of the heat sink and are connected to a set of fins. The structure is characterized in a plurality of conductor blocks formed on the heat sink at two sides of each heat pipe to aid heat absorption of the heat pipe. Therefore, the lifetime of the heat pipes are prolonged, and the heat dissipation performance is enhanced.